

Announcing 3D-PEIM 2026 Tutorial and Panel Session



3D-PEIM 2026, the premier international symposium dedicated to 3D power electronics packaging and heterogeneous integration, will take place November 16–19, 2026, at Arizona State University in Tempe, Arizona. The symposium will bring together researchers, manufacturers, and industry leaders to discuss emerging technologies and manufacturing approaches shaping the future of advanced power packaging.

As part of the 2026 technical program, the Organizing Committee is pleased to announce the addition of four expert-led tutorials and a special panel session to be held on Monday, November 16. The tutorial program will provide attendees with in-depth perspectives on key technical challenges and industry developments across advanced packaging, reliability, materials, and system integration.

Tutorial presentations will include **Advanced Packaging**, presented by George Dogiamis (Deca Technologies), Chanyeop Park (ASU), Hongbin Yu (ASU), and Chris Bailey (ASU); **Die-Attach by Metal Powder Sintering: The Science and Practice** by G.-Q. Lu (Virginia Tech); **Digital Twin-Driven Reliability and Prognostics in Power Electronics Systems** by Jong Eun Ryu (North Carolina State University); and **Trends in Magnetic Material Properties to Meet the Challenges of Supporting High-Performance Computing** by Matt Wilkowski (Würth Electronics). Tutorials will be held from 1:00 PM to 5:15 PM, with registration available during the conference registration process opening in June. Attending the tutorials and panel session is free. Conference registration is not required.

Following the tutorials, 3D-PEIM 2026 will host a panel session titled “**Key Challenges for 3D Power Electronics Packaging/Manufacturing**,” featuring academic and industry experts discussing current manufacturing, reliability, and integration challenges facing next-generation power electronics systems. Tentatively confirmed panel participants include Ravi Mahajan (Intel/HIR Chair), Doug Hopkins (North Carolina State University/HIR Power Chapter), Chris Bailey (Arizona State University/HIR Modeling and Simulation Chapter), Pat McCluskey (University of Maryland/HIR Thermal Chapter), George Dogiamis (Deca Technologies), and Francesco Carobolante (IoTissimo).

The 2026 symposium will also feature six plenary speakers, seven technical sessions, poster presentations, industry exhibits, and guided tours of ASU’s MacroTechnology Works facility. Technical focus areas include advanced packaging and 3D integrated modules, thermal management, design and simulation, reliability and failure analysis, passive components, power delivery and energy storage, and materials for advanced packaging.

Conference registration will open June 8, 2026. Additional information regarding sponsorship opportunities, exhibitor participation, and registration can be found at <https://www.3d-peim.org/>.

We look forward to welcoming attendees to Arizona State University for 3D-PEIM 2026.